Messrs. Digi-Key

| Issue No. | : | PC-02-060 |
|--------------------|---|-----------------------|
| Date of issue | • | November 15, 2002 |
| Classification | : | ■ New□Change□ Renewal |

Delivery Specification

| Product Description | : Balun |
|------------------------|---|
| Product Part Number | : EHF1BG1800 |
| Classification of Spec | : Individual Product Specification |
| Applications | : Cellular phone |
| | For other applications, contact the undersigned in advance. |
| Term of Validity | : November 14, 2007 from the date of issue. |

| CUSTOMER USE ONLY | Receipt Record#: |
|---|------------------|
| This was certainly received by us. 1(one) copy is being returned to you. | Date of receipt: |
| r(one) copy is boing retained to you. | Received by: |
| | Title: Dept.: |

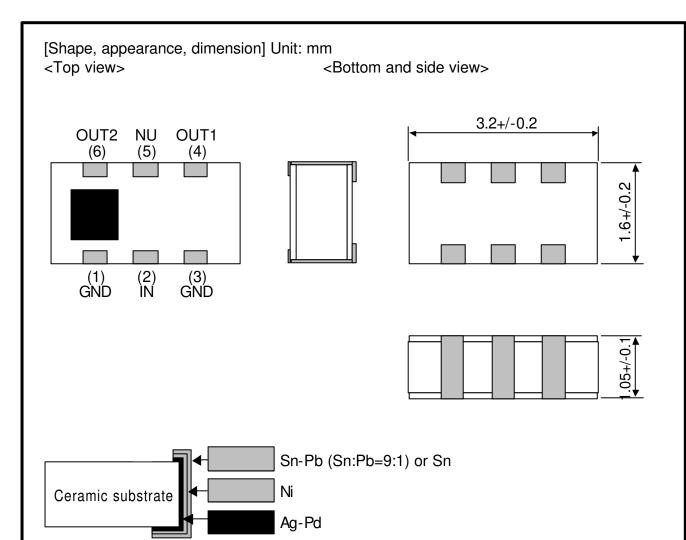
Matsushita Electronic Components Co., Ltd. Network Device Company Module Strategic Business Unit Engineering Group HFD Team

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Tel: +81-0585-36-2322 Fax: +81-0585-36-2344 Prepared by : H. Ito Checked by : M. Mizuno

Authorized by : M. Mizuno

Title : Manager of Engineering



Note 1) "typ" is used where no dimensional tolerance applies.

| Item | Description | | | | | |
|---------------------------------|--|--|--|--|--|--|
| Appearance/ construction | Product surface shall be covered with a protective film, which does not easily separate nor present noticeable unevenness, scratches, pinholes, color changes etc. | | | | | |
| | Terminals shall ensure practically acceptable quality. | | | | | |
| | Substrate shall be as shown in the drawing with no excessive chippings, scratches, burrs, or cracks. | | | | | |
| Marking | Shall be legible in black (with printing paste). | | | | | |
| Remarks marked side for pin 1. | | | | | | |

| Balun | | Delive | y Specif | ication | EHF1BG1800 |
|-------------------------------|-------|-----------|-----------|---------|------------------------------------|
| Enact. Date November 15, 2002 | P.S.M | Approval | Check | Plan | Appearance |
| Enfo. Date November 15, 2002 | | M. Mizuno | M. Mizuno | H. Ito | Drawing No. 151-EHF-1BG1800 9-1 |

[Absolute maximum ratings]

| No. | Item | Symbol | Rating | Unit | Remarks |
|-----|-----------------------|--------|--------|------|-------------------|
| 1 | Maximum input power | Pmax | 100 | mW | DC voltage is 0V. |
| 2 | Operating temperature | Topr | -30+85 | degC | |
| 3 | Storage temperature | Tstg | -40+85 | degC | |

Note: This component cannot apply a DC Bias.

[Electrical characteristics]

T=-30...+85degC

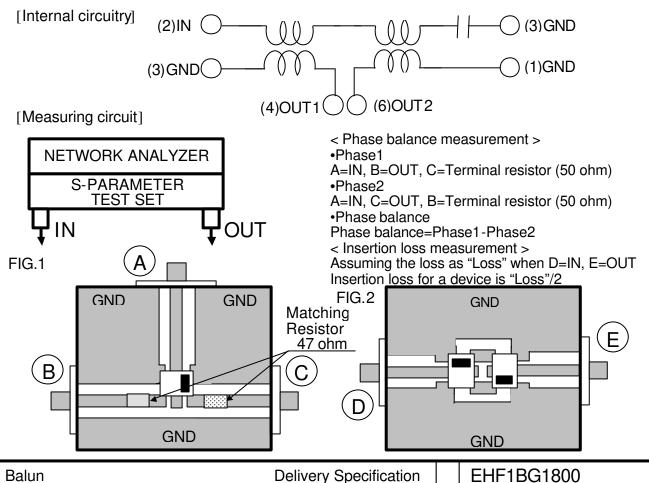
Specification and measurement

151-EHF-1BG1800

9-2

Drawing No.

| No. | Item | Test | | Specification | | | | | |
|-----|-------------------------------|---------|------|---------------|------|-----|--|--|--|
| | | Circuit | Min. | Тур. | Max. | | | | |
| 1 | Frequency | - | 1700 | - | 1900 | MHz | | | |
| 2 | Insertion loss (Back to back) | Fig-2 | ı | - | 0.8 | dB | | | |
| 3 | Unbalance impedance | ı | - | 50 | - | ohm | | | |
| 4 | Balance impedance | ı | ı | 200 | ı | ohm | | | |
| 5 | Unbalance port VSWR | Fig-1 | 1 | - | 2.0 | - | | | |
| 6 | Amplitude balance | Fig-1 | -1.0 | _ | 1.0 | dB | | | |
| 7 | Phase balance | Fig-1 | 170 | 180 | 190 | deg | | | |



P.S.M

Enact. Date November 15, 2002

Enfo. Date November 15, 2002

Approval

M. Mizuno

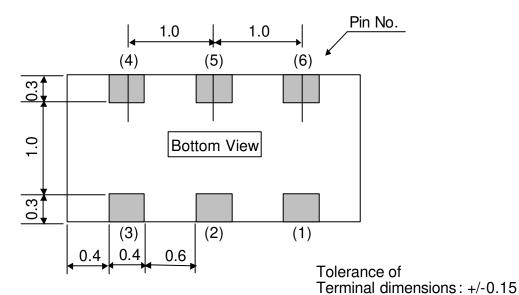
Check

M. Mizuno

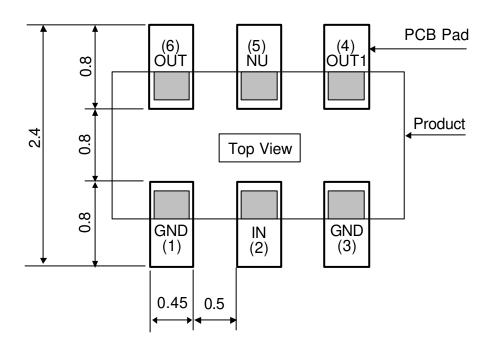
H. Ito

[Terminal dimensions] Unit: mm

<Bottom>



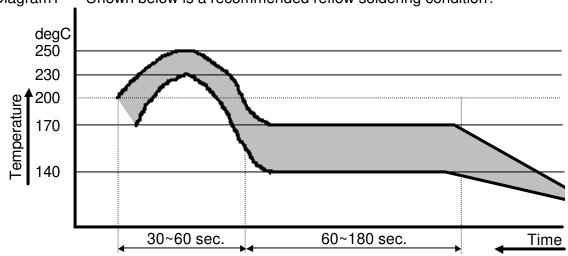
[Recommended PCB pad dimensions] Unit: mm



| Balun | | Deliver | y Specifi | cation | EHF1BG1800 |
|-------------------------------|-------|-----------|-----------|--------|------------------------------------|
| Enact. Date November 15, 2002 | P.S.M | Approval | Check | Plan | Terminals/Recommended lands |
| Enfo. Date November 15, 2002 | | M. Mizuno | M. Mizuno | H. Ito | Drawing No. 151-EHF-1BG1800 9-3 |

| [Quality characteristic | s] | | |
|--|---|---|--|
| Test item | Test condition | Judgment criteria | |
| High temperature | +85degC, 1000h | No abnormality shall be observed in | |
| Low temperature | -40degC, 1000 h | appearance or | |
| High-temperature high-humidity storage | +60degC, 90%RH, 1000h | electrical characteristics. | |
| Pressure Pot | +121degC, 99%RH, 2.026x10 ⁵ Pa, 100h | Characteristics. | |
| Temperature cycling | -40+85degC, Each 30 min., 200cy | | |
| Vibration | 10500Hz, 10G, in each direction of XYZ, 2h30min. | | |
| Impact | 100G, 6mS, Half sinusoidal wave, in each direction of XYZ, 3 times | | |
| Shock (Drop) | 1.8m, 6 facesx6cy(36 times with 100g Dummy Load) | | |
| Electro static discharge | 200pF, 0 ohm, +/-200V, Each 5 times | | |
| Soldering heat resistance | Manual hot gas: 260+/-10degC, 30 sec., 2 times | Over 90% of the terminal surface shall be covered with solder. | |
| | Soldering iron: 260+/-10degC, 3 sec., 2 times | | |
| | Reflow: 260degC peak, 2 times | | |
| Solder ability | Solder bath: 235+/-5degC, 2 sec. | Over 95% of the terminal surface shall be covered | |
| | Reflow: 230degC | with solder. | |
| Board warping | Assemble this component on a PC board with 0.8mm thickness using the recommended soldering condition shown below, and apply a bending force of 3mm warping at a rate of 1mm/sec. 5 seconds and 5 times. 45mm 45mm 45mm | There should not be any cracks in the component or solder joints, no abnormality in electrical characteristics. | |
| Terminal removal | condition shown below and nit 9.8N or greater. | | |
| Seating plane co-planarity | Within 0.1mm | | |





| Balun | | Delive | y Specif | ication | EHF1BG1800 |
|-------------------------------|-------|-----------|-----------|---------|------------------------------------|
| Enact. Date November 15, 2002 | P.S.M | Approval | Check | Plan | Quality Characteristics |
| Enfo. Date November 15, 2002 | | M. Mizuno | M. Mizuno | H. Ito | Drawing No. 151-EHF-1BG1800 9-4 |

[Cautions for use]

- (1) Operating a product over the maximum rating for even a moment may result in a product failure or breakage. Never use a product in such a condition that it may cause a safety problem.
- (2) Opening or short-circuiting the product terminals or inserting a product in the reverse orientation while power is being supplied may cause a breakage. Always avoid such circumstances.
- (3) Operations in a corrosive gas atmosphere or improper environments such as high-temperature, high-humidity or dewy conditions may lead to product performance deterioration, a breakage, a change in appearance etc. Please avoid such conditions, as they are unsafe.
- (4) Always ground the soldering iron or soldering bath used for assembly operation to avoid any excessive voltage applied to a product.
- (5) After soldering with solder bridges, incomplete soldering or in the reverse orientation, supplying power may result in a product breakage. Please confirm the soldered condition before supplying power to the product.
- (6) Excessive stress on the terminals may cause a contact failure or performance deterioration. Please use caution.
- (7) Please provide a fail-safe provision in the product you design by taking any failure of our product into consideration.
- (8) This product does not include a DC-cutting device. Application of a DC voltage between the Balance port and the Unbalance port may cause product deterioration or breakage.
 - * If any question arises about the safety of this product, please contact us immediately with a request for an engineering examination.

[Remarks]

- *1: All of the materials used in this product are those listed as the existing chemical substances based on the "Law for examination and regulation of manufacture of chemical substances".
- *2: The production process of this product does not use any ozone-depleting chemicals (OZC) regulated by the Montreal Protocol.
- *3: Validity of this specification is 5 years from the date of issue, but the validity is considered on going unless any changes are made.

| Balun | | Deliver | y Specif | cation | EHF1BG1800 |
|-------------------------------|-------|-----------|-----------|--------|------------------------------------|
| Enact. Date November 15, 2002 | P.S.M | Approval | Check | Plan | Cautions |
| Enfo. Date November 15, 2002 | | M. Mizuno | M. Mizuno | H. Ito | Drawing No. 151-EHF-1BG1800 9-5 |

[Packaging materials] 1. Materials 1)

- Embossed carrier tape (Refer to the attachment)
 Top tape: Anti-static
 Packaging box (Refer to the attachment)
 Packaging tape, carrier-securing adhesive tape

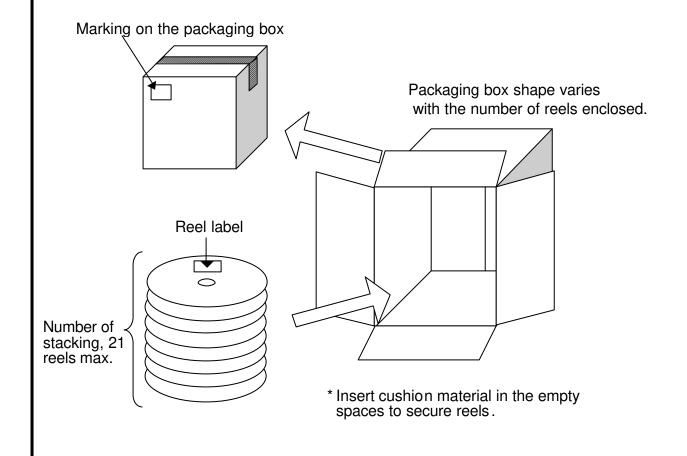
2. Specification

| No. | Item | Condition | Remarks |
|-----|---|--|---|
| 1 | Reel outer diameter | Refer to the attachment. | |
| 2 | | Refer to the attachment. | |
| 3 | | Refer to the attachment. | |
| 4 | Quantity in a reel | 3000 pieces/reel | |
| 5 | Taping direction | Tape unreeling direction (with markings facing up) | |
| 6 | Top tape attachment position | Top tape 8.0+/-0.2mm 5.5mm Top tape Top tape attachment area > Embossed tape Top tape edge must stay inside the sprocket holes of the embossed carrier (Sprocket holes shall not be covered). | Tape breaks force. Min. 10N Top cover tape strength. Min. 10N Tape peel force. 0.11.0N Tape peel angle. 165180degree Reel weight. Max 1500g |
| 7 | Label attachment position | Tape unreeling direction | Indicated Item Pat No., Lot No. Quantity, Maker Country |
| 8 | Tape leader part and tape ending part | Leader part Leader part | - |
| 9 | Missing products | No missing products shall be allowed. | |
| 10 | Packaged quantity in a box | 21 reels/box (Max) | 63000 pieces/box(Max) |
| | | | |

| Balun | Delivery Specification | | | | | EHF1BG1800 | |
|-------------------------------|------------------------|-----------|-----------|--------|--|------------------------------------|--|
| Enact. Date November 15, 2002 | P.S.M | Approval | Check | Plan | | Packaging specification 1 | |
| Enfo. Date November 15, 2002 | | M. Mizuno | M. Mizuno | H. Ito | | Drawing No. 151-EHF-1BG1800 9-6 | |

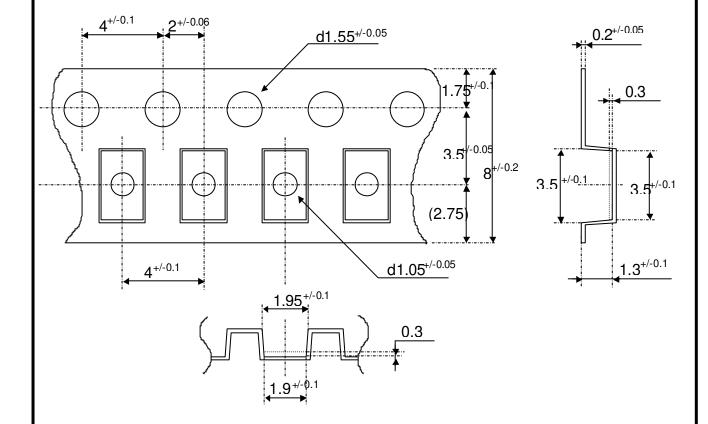
1. Method

- 1) Load products in each cavity of an embossed carrier tape, in the correct orientation, by leaving the product-unloaded part shown in Item No. 8(P9-6) of the packaging specification.
- 2) Heat-seal a top tape in good alignment on the carrier tape.
- 3) After 3000 pieces are loaded and reeled, provide a product-unloaded part at the tape-leader portion. Secure the tip of the carrier tape with a piece of adhesive tape.
- 4) Stack the reels (21 reels max.) and enclose them in a packaging box. Close the flaps with a piece of adhesive tape.
- 5) Provide markings on the packaging box.
 - < Items to be indicated >
 - 1. Part No.
 - 2. Quantity
 - 3. Lot No.
 - 4. Manufacturer name
 - 5. Country of origin



| Balun | Delivery Specification | | | | EHF1BG1800 |
|-------------------------------|------------------------|-----------|-----------|--------|------------------------------------|
| Enact. Date November 15, 2002 | P.S.M | Approval | Check | Plan | Packaging specification 2 |
| Enfo. Date November 15, 2002 | | M. Mizuno | M. Mizuno | H. Ito | Drawing No. 151-EHF-1BG1800 9-7 |

[Embossed tape dimensions] Unit: mm



<Remarks>

- (1) Unspecified corner radius shall be 0.3mm max.
- (2) Cumulative pitch error of sprocket holes shall be +/-0.2mm for 10 pitches.

| Balun Delivery Specification | | | | | EHF1BG1800 | |
|-------------------------------|-------|-----------|-----------|--------|------------------------------------|--|
| Enact. Date November 15, 2002 | P.S.M | Approval | Check | Plan | Packaging specification 3 | |
| Enfo. Date November 15, 2002 | | M. Mizuno | M. Mizuno | H. Ito | Drawing No. 151-EHF-1BG1800 9-8 | |

